

0.5A Avg.

30 Volts

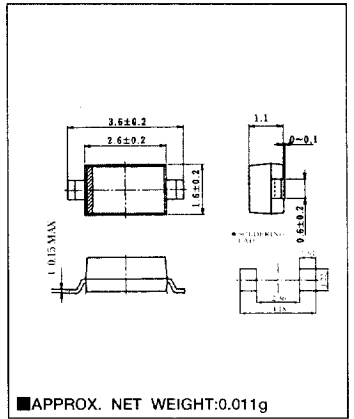
SBD

EP05Q03L

■最大定格 MAXIMUM RATINGS

Rating	Symbol	Type	EP05Q03L	Unit
繰り返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}		30	V
平均整流電流 Average Rectified Output Current	Substrate mounted *	I_O	0.49 (商用周波数、正弦波180度通電 $T_a=25^{\circ}C$) Half Sine Wave, Resistive Load	A
			0.50 (商用周波数、正弦波180度通電 $T_l=106^{\circ}C$) Half Sine Wave, Resistive Load (Tl: Lead Temperature)	A
実効順電流 RMS Forward Current	$I_{F(RMS)}$		0.785	A
サージ順電流 Surge Forward Current	I_{FSM}		8 (50Hz单相正弦半波1サイクル非くり返し) Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}		-40~+150	$^{\circ}C$
保存温度範囲 Storage Temperature Range	T_{stg}		-40~+150	$^{\circ}C$

■OUTLINE DRAWING(mm)



■電気的特性 ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$V_{RM}=V_{RRM}$ $T_j=25^{\circ}C$	—	—	200	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$I_{FM}=0.5A$ $T_j=25^{\circ}C$	—	—	0.45	V
熱抵抗 Thermal Resistance	接合部-周囲間 (Junction to Ambient)	Glass-Epoxy Substrate mounted *	—	—	300	$^{\circ}C/W$
	接合部-リード間 (Junction to Lead)		—	—	70	$^{\circ}C/W$

*Soldering Lands = 1×1 mm, Both Sides

■定格・特性曲線

FIG.1

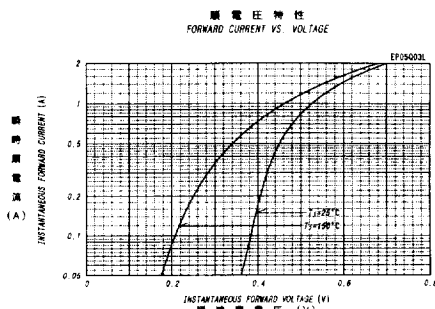


FIG.4

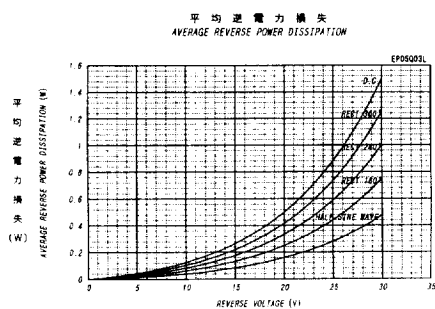


FIG.7

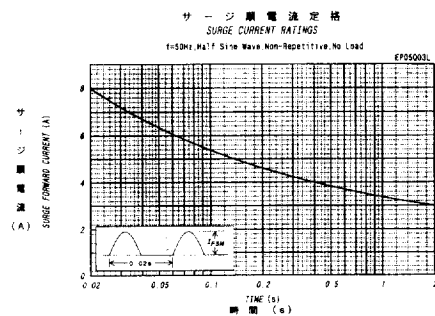


FIG.2

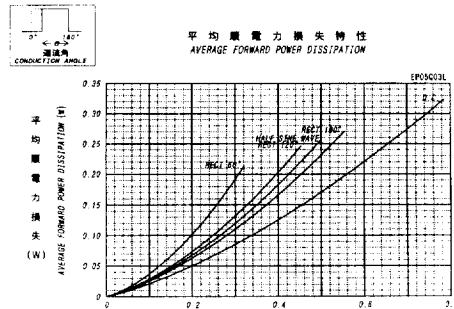


FIG.5

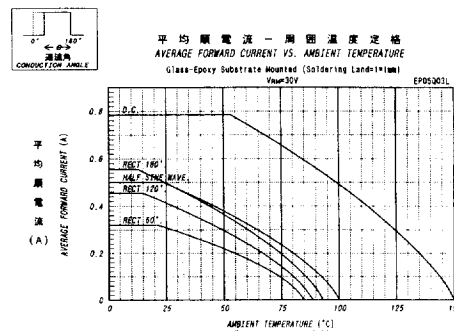


FIG.8

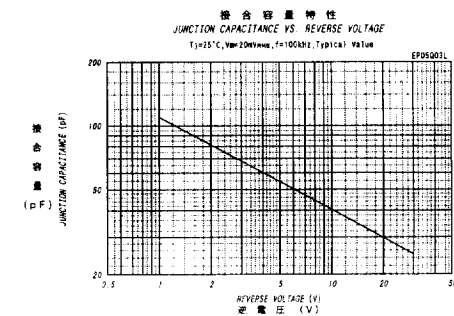


FIG.3

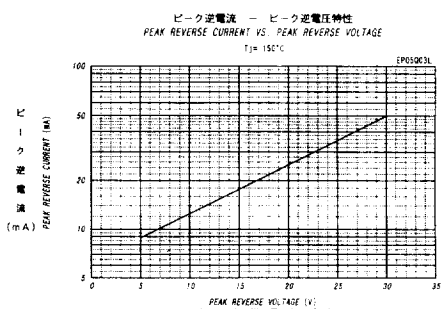


FIG.6

